

WHAT IS CLAIMED IS:

1. A method for manufacturing a multilayer circuit component which comprises at least two glass-containing layers on a substrate, in which the baking shrinkage rates of the first glass-containing layer and second glass-containing layer formed are about the same, comprising:

(a) applying and drying a first photosensitive glass paste comprising glass having a softening temperature and a photosensitive vehicle to a substrate;

(b) forming a via hole pattern on the resulting dried first paste;

(c) baking the resulting paste with said via hole pattern so as to form a first glass-containing layer;

(d) applying and drying a second photosensitive glass paste comprising glass having a softening temperature and a photosensitive vehicle, on said first glass-containing layer;

(e) forming a via hole pattern on the resulting dried second paste; and

(f) baking the resulting second paste with said via hole pattern so as to form a second glass-containing layer;

wherein at least one parameter selected from glass softening temperature and glass content in the first glass paste is different from the same parameter in the second glass paste, whereby the baking shrinkage rates of the first glass-containing layer and second glass-containing layer formed are about the same.

2. A method for manufacturing a multilayer circuit component according to Claim 1, wherein the glass softening temperature parameter in the first glass paste is different from the glass softening temperature parameter in the second glass paste.

3. A method for manufacturing a multilayer circuit component according to Claim 2, wherein the glasses in the pastes are such that

the glass of the first glass-containing layer has a contact angle relative to said substrate which is larger than the contact angle of the glass of the second glass-containing layer

relative to said first glass-containing layer; and

the softening temperature of the glass in the first photosensitive glass paste is lower than the softening temperature of the glass in the second photosensitive glass paste.

4. A method for manufacturing a multilayer circuit component according to Claim 2, wherein the glasses in the pastes are such that

the glass of the first glass-containing layer has a contact angle relative to said substrate which is smaller than the contact angle of the glass of the second glass-containing layer relative to said first glass-containing layer; and

the softening temperature of the glass in the first photosensitive glass paste is higher than the softening temperature of the glass in the second photosensitive glass paste.

5. A method for manufacturing a multilayer circuit component according to Claim 2, wherein the difference between the softening temperature of the glass in the first photosensitive glass paste and the softening temperature of the glass in the second photosensitive glass paste is at least about 30°C.

6. A method for manufacturing a multilayer circuit component according to Claim 1, wherein the glass content in the first glass paste is different from the glass content in the second glass paste.

7. A method for manufacturing a multilayer circuit component according to Claim 6, wherein the first and second photosensitive glass pastes each comprise low softening temperature glass and the low softening temperature glass content in the first and second photosensitive glass pastes are different.

8. A method for manufacturing a multilayer circuit component according to Claim 7, wherein the first and second photosensitive glass pastes each comprise ceramic.

9. A method for manufacturing a multilayer circuit component according to Claim 1, wherein the glass in each of the first and second photosensitive glass pastes comprise low softening temperature glass.

10 A method for manufacturing a multilayer circuit component according to Claim 1, wherein the glass in the first photosensitive glass paste comprises low softening temperature glass.

11. A method for manufacturing a multilayer circuit component according to Claim 1, wherein the first and second photosensitive glass pastes each comprise ceramic.

12. A method for manufacturing a multilayer circuit component according to Claim 11, wherein the substrate is a glass-free ceramic.

13. A method for manufacturing a multilayer circuit component according to Claim 12, wherein the glass in the first photosensitive glass paste comprises low softening temperature glass.

14. A method for manufacturing a multilayer circuit component according to Claim 13, wherein the glass in the second photosensitive glass paste comprises low softening temperature glass.

15. A method for manufacturing a multilayer circuit component according to Claim 14, wherein the glass content in the first glass paste is different from the glass content in the second glass paste.

16. A method for manufacturing a multilayer circuit component according to Claim 14, wherein the glass softening temperature parameter in the first glass paste is different from the

glass softening temperature parameter in the second glass paste.

17. A method for manufacturing a multilayer circuit component according to Claim 16, wherein the glass softening temperature parameters differ be at least about 30°C.

18. A method for manufacturing a multilayer circuit component according to Claim 1, wherein the substrate is a glass-free ceramic.

19. A method for manufacturing a multilayer circuit component according to Claim 18, wherein the glass content in the first glass paste is different from the glass content in the second glass paste.

20. A method for manufacturing a multilayer circuit component according to Claim 19, wherein the in the first glass paste is different from the glass in the second glass paste.